

AMENDMENTS TO THE CLAIMS

The following Listing of Claims will replace all prior versions, and listing of claims in the Application.

Listing of Claims:

1. (Withdrawn) An anti-microbial sanitary ware comprising:

 a substrate; and

 an anti-microbial film formed on said substrate and comprising a protective layer and anti-microbial metal particles that are dispersed in said protective layer;

 wherein said protective layer is made from a compound selected from the group consisting of metal nitrides and metal carbides; and

 wherein said anti-microbial metal particles are made from a metal selected from the group consisting of silver, zinc, and copper.
2. (Withdrawn) The anti-microbial sanitary ware of Claim 1, wherein said compound of said protective layer is metal nitride.
3. (Withdrawn) The anti-microbial sanitary ware of Claim 2, wherein said compound is selected from the group consisting of zirconium nitride, chromium nitride, and titanium nitride.

4. (Withdrawn) The anti-microbial sanitary ware of Claim 3, wherein said compound is zirconium nitride.

5. (Withdrawn) The anti-microbial sanitary ware of Claim 4, wherein said substrate is made from a material selected from the group consisting of copper alloy, zinc alloy, stainless steel, ceramics, and plastics.

6. (Withdrawn) The anti-microbial sanitary ware of Claim 5, wherein said substrate is made from copper alloy.

7. (Currently Amended) A method for making an anti-microbial sanitary ware, comprising the steps of:

placing a substrate in a sputtering chamber in a sputter; ~~and~~
simultaneously sputtering a first metal target of a first metal and a second metal target of a second metal through closed-field unbalanced magnetron sputtering techniques; ~~which form~~

forming a continuously closed magnetic field around the substrate; ;
~~so as to react~~

reacting the first metal into a metal compound ~~which is~~ and
subsequently depositing said metal compound ~~deposited~~ on the substrate thereby
forming to form a protective layer; and

generating ~~, and so as to generate~~ metal particles of the second metal having a size of less than 100 nanometers and dispersing said metal particles that ~~are dispersed~~ in the protective layer;

wherein the second metal is selected from the group consisting of silver, zinc, and copper; and

wherein the metal compound is selected from the group consisting of metal nitrides and metal carbides.

8. (Original) The method of Claim 7, wherein the first metal is selected from the group consisting of zirconium, chromium, and titanium.

9. (Original) The method of Claim 8, wherein the metal compound is selected from the group consisting of zirconium nitride, chromium nitride, and titanium nitride.

10. (Original) The method of Claim 9, wherein the substrate is made from a material selected from the group consisting of copper alloy, zinc alloy, stainless steel, ceramics, and plastics.

11. (Original) The method of Claim 10, wherein the sputtering for the first metal target is conducted at a voltage ranging from 20-50V, and a current ranging from 3.5-4.5A.

12. (Original) The method of Claim 11, wherein the sputtering for the second metal target is conducted at a voltage of less than 20V, and a current ranging from 0.3-0.5A.

13. (Original) The method of Claim 12, wherein the sputtering is conducted at a temperature ranging from 80-180°.

14. (Original) The method of Claim 13, wherein the sputtering is conducted at a pressure ranging from 0.1-20 mTorr.

15. (Original) The method of Claim 14, wherein the sputtering time ranges from 3-13 minutes.